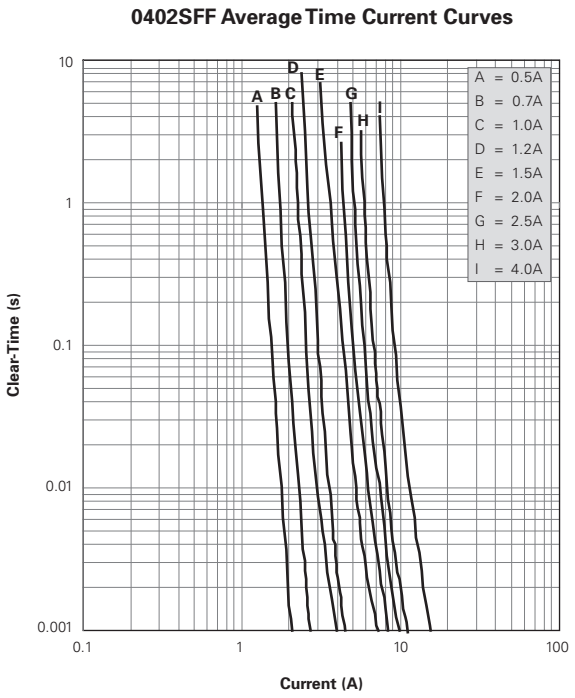
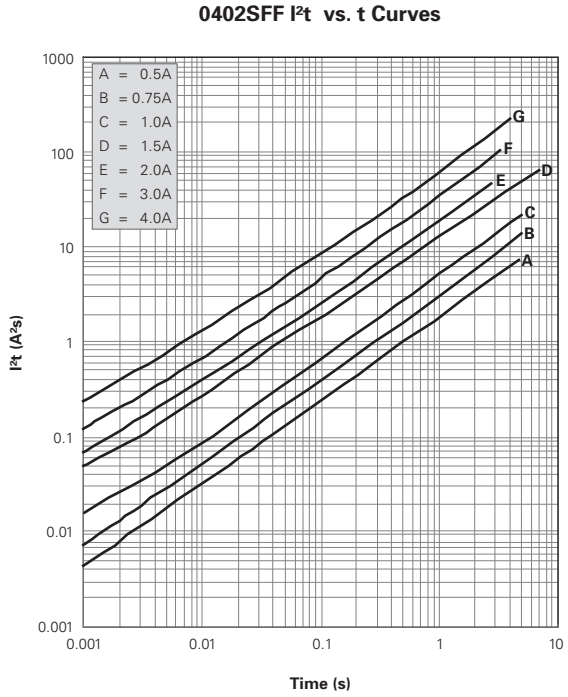
## Figure FF1-FF6 Family Performance Curves

### Figure FF1

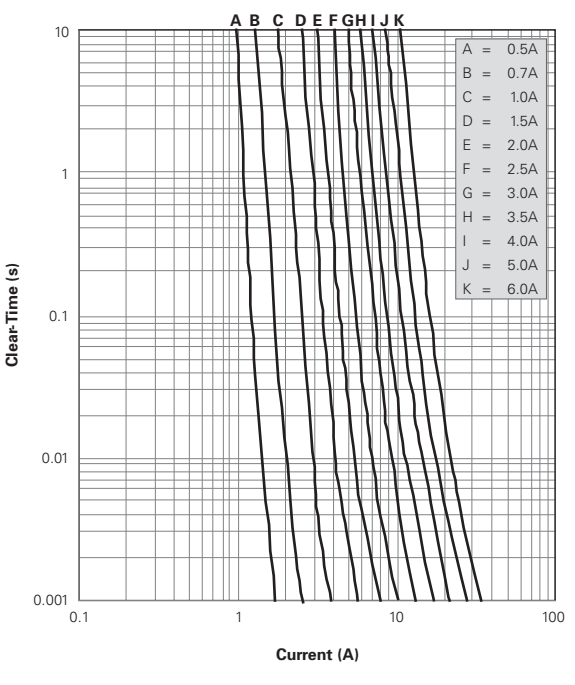



### Figure FF2

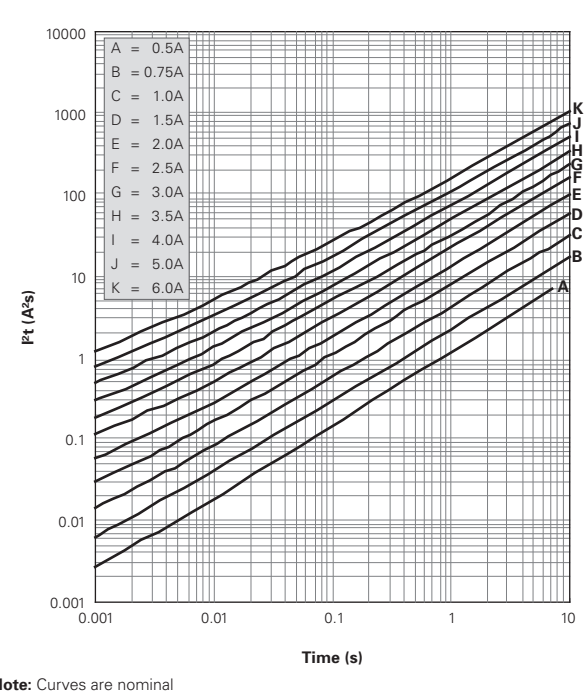



**Note:** Curves are nominal

### Figure FF3



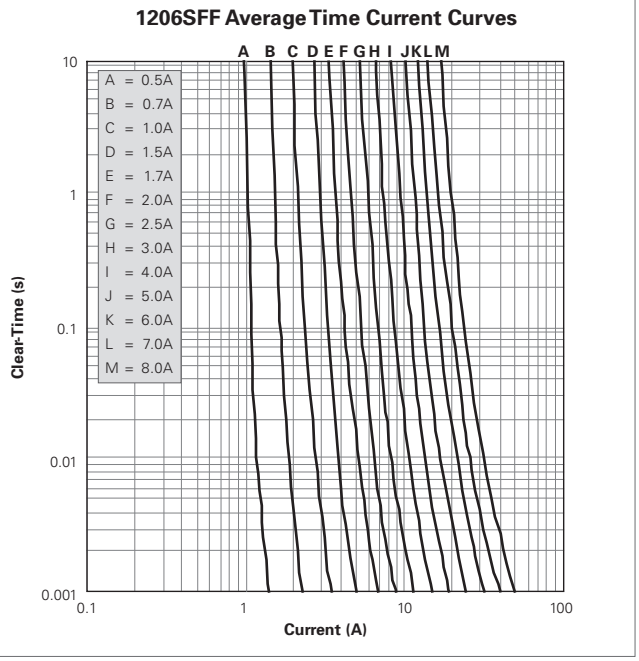

### Figure FF4



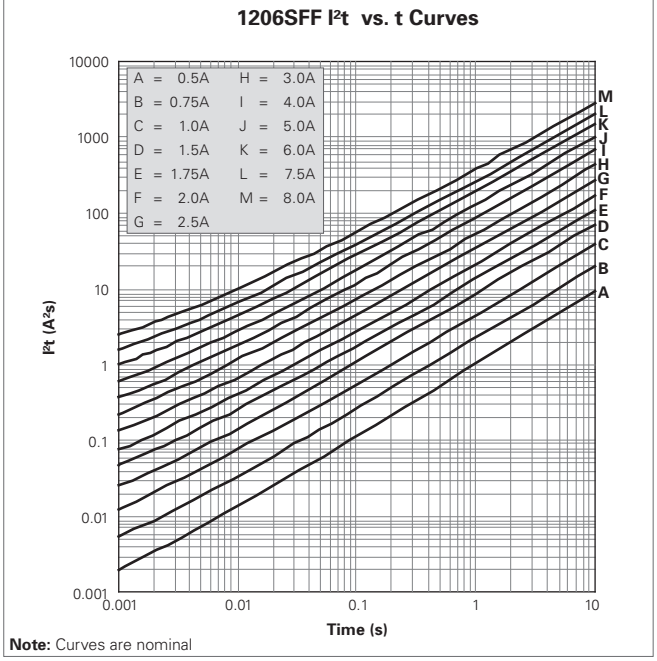

**Note:** Curves are nominal

## Figure FF1-FF6 Family Performance Curves ... Cont'd

### Figure FF5




### Figure FF6




**Note:** Curves are nominal

## Table FF3 Environmental Specifications for Fast-Acting Chip Fuses

| | |
|---|---|
| Operating temperature | -55°C to +125°C |
| Mechanical vibration | Withstands 5-3000 Hz at 30 Gs when evaluated per Method 204 of MIL-STD-202 |
| Mechanical shock | Withstands 1500 Gs, 0.5 millisecond half-sine pulses when evaluated per Method 213 of MIL-STD-202 |
| Thermal shock | Withstands 100 cycles from -65°C to +125°C when evaluated per Method 107 of MIL-STD-202 |
| Resistance to soldering heat | Withstands 60 seconds at +260°C when evaluated per Method 210 of MIL-STD-202 |
| Solderability | Meets 95% minimum coverage requirement when evaluated per Method 208 of MIL-STD-202 |
| Moisture resistance | Withstands 10 cycles when evaluated per Method 106 of MIL-STD-202 |
| Salt spray | Withstands 48-hour exposure when evaluated per Method 101 of MIL-STD-202 |

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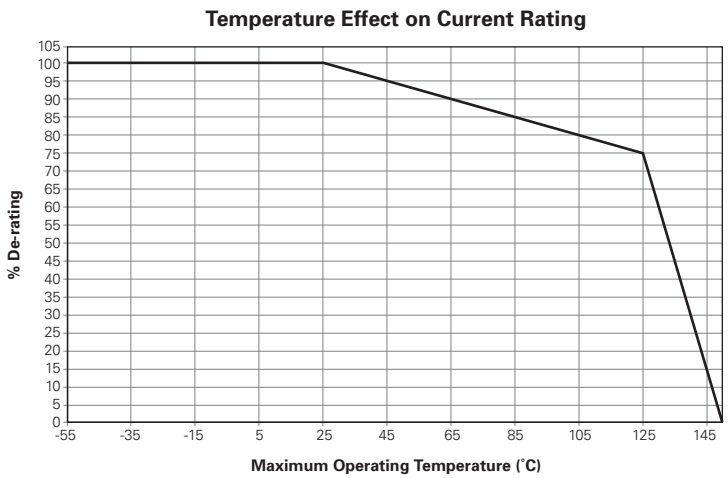
## Table FF4 Material Specifications for Fast-Acting Chip Fuses

| | |
|---|---|
| Construction body material | Ceramic |
| Termination material | Silver, Nickel, Tin |
| Fuse element | Silver |

## Figure FF7 Thermal Derating Current for Fast-Acting Chip Fuses






RoHS Compliant, ELV Compliant HF Halogen Free